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(54) **HIGH SPEED HIGH DENSITY CONNECTOR ASSEMBLY**

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H01R 12/71 (2011.01)

H01R 13/6474 (2011.01)

(52) **U.S. Cl.**

CPC **H01R 13/6587** (2013.01); **H01R 12/718** (2013.01); **H01R 13/6474** (2013.01); **Y10S 439/931** (2013.01)

(58) **Field of Classification Search**

CPC H01R 13/65807; H01R 13/658; H01R 23/688; H01R 23/6873; H01R 23/7073

See application file for complete search history.

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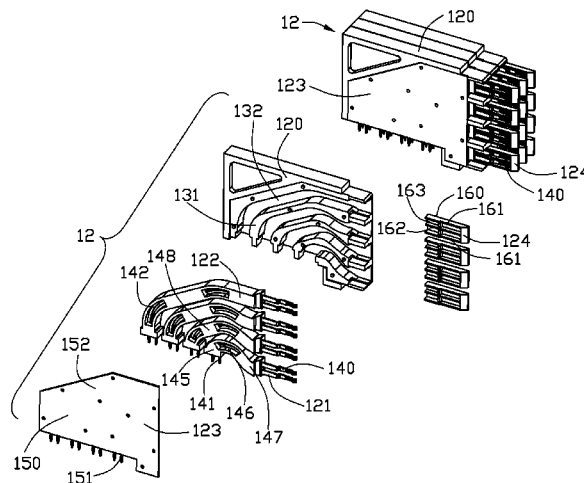
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(57) **ABSTRACT**

An electrical connector (50; 70; 80; 90; 91) includes a number of contact wafers (502; 61; 71; 822; 920) stacked with each other along a transverse direction. Each contact wafer includes a conductive body, one or more shielding members (53; 68; 720; 900) mounted to and electrically connecting with the conductive body, and a number of contact modules each including an insulator (550; 621) and a pair of contacts (551; 620; 921) fixed by the insulator, the pair of contacts of each contact module being shielded by the conductive body and the one or more shielding members.

17 Claims, 18 Drawing Sheets



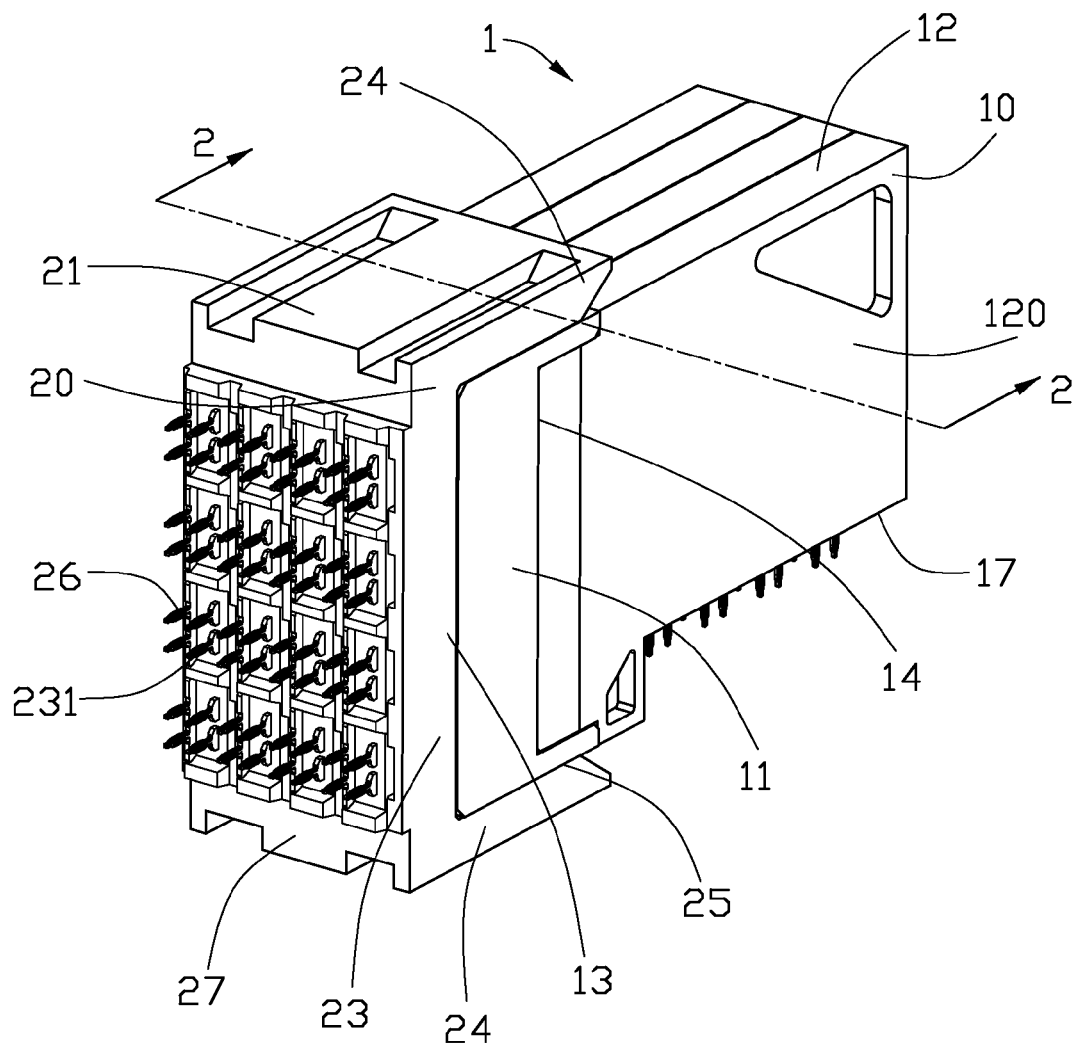


FIG. 1

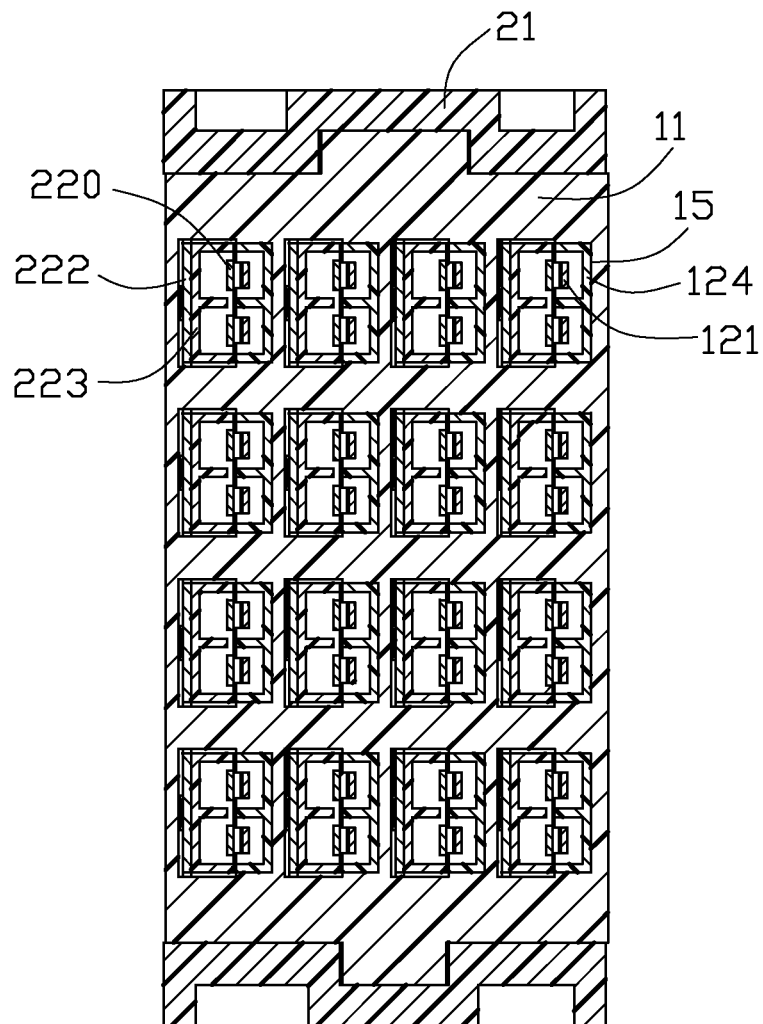
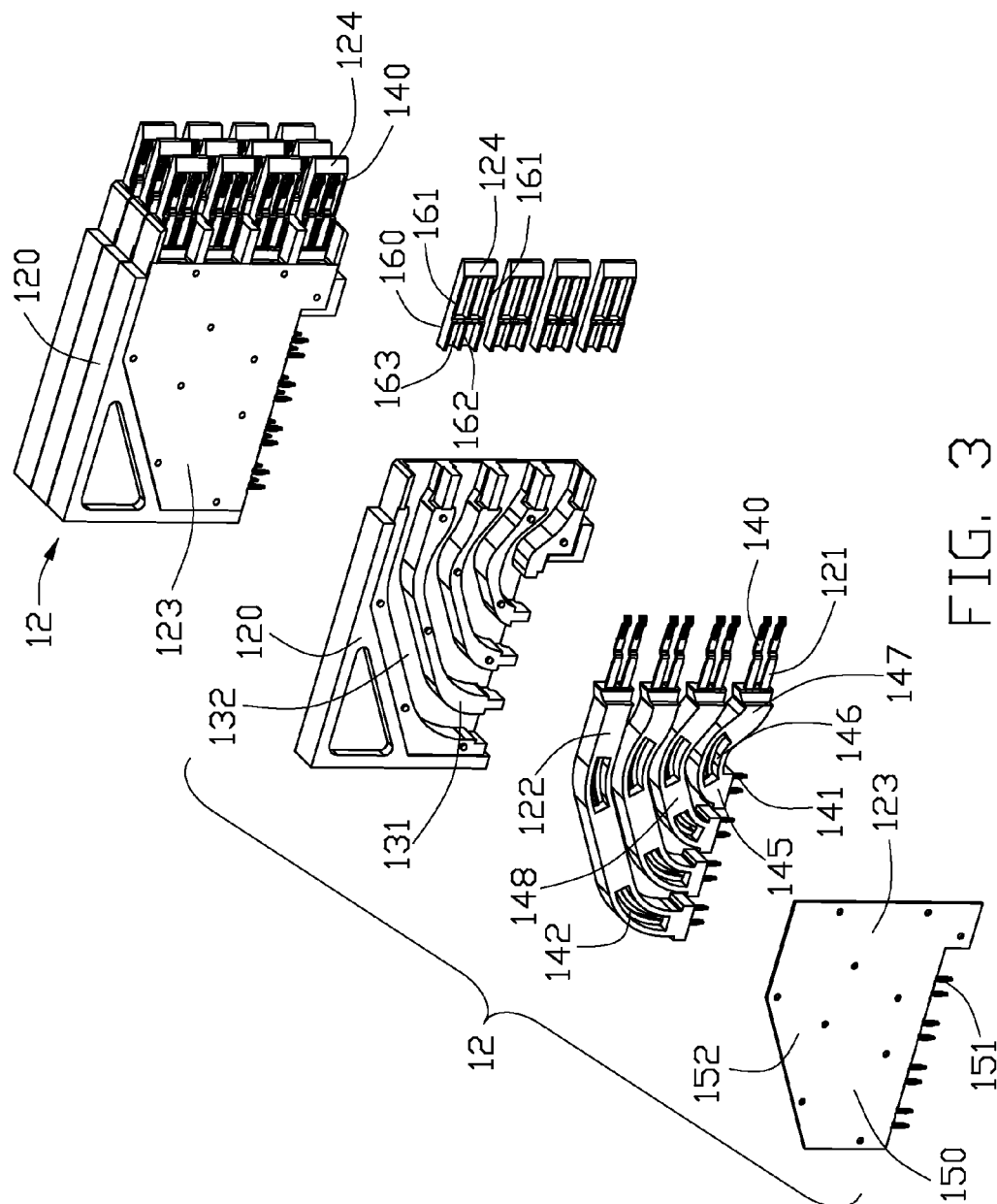
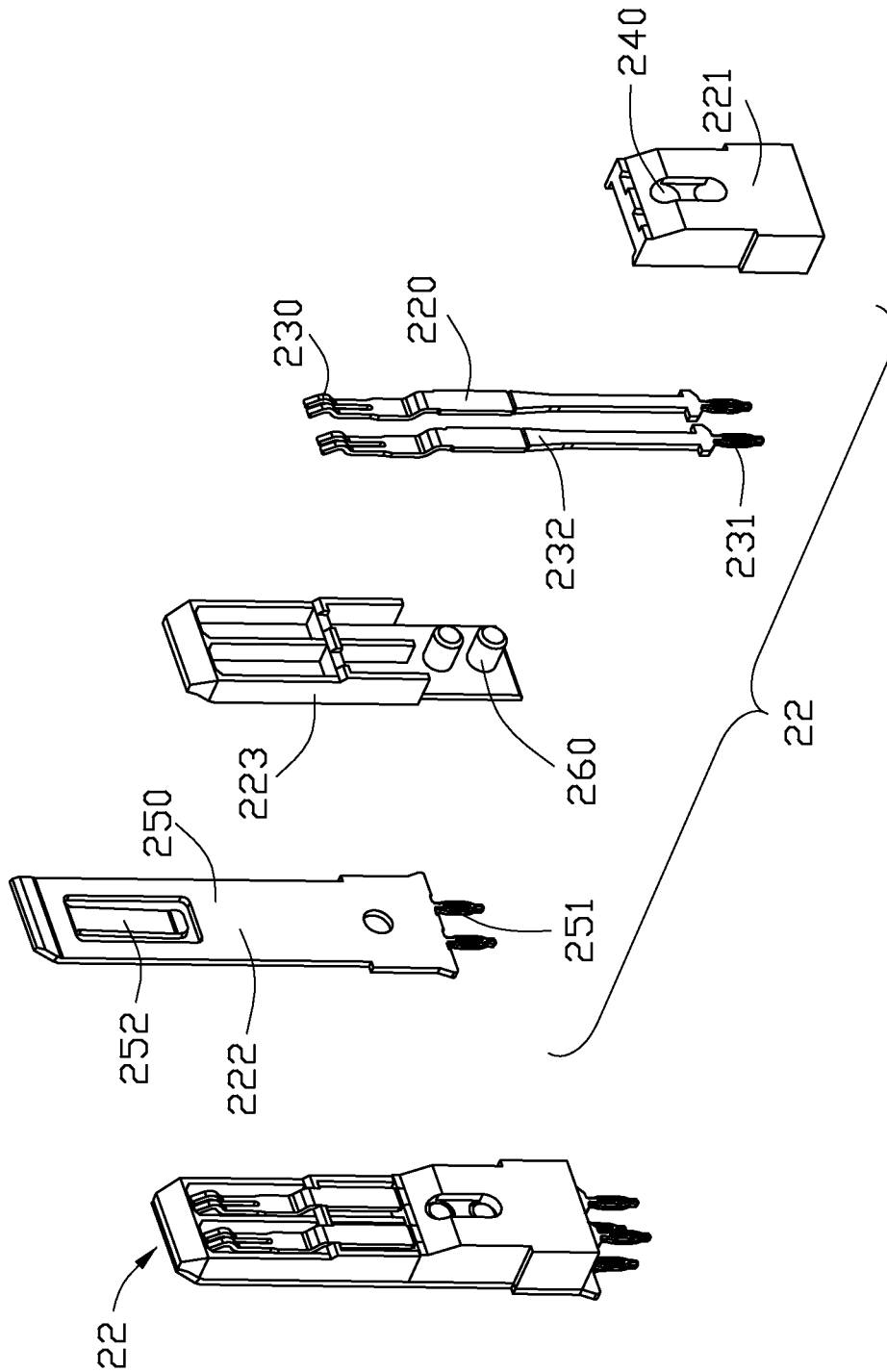
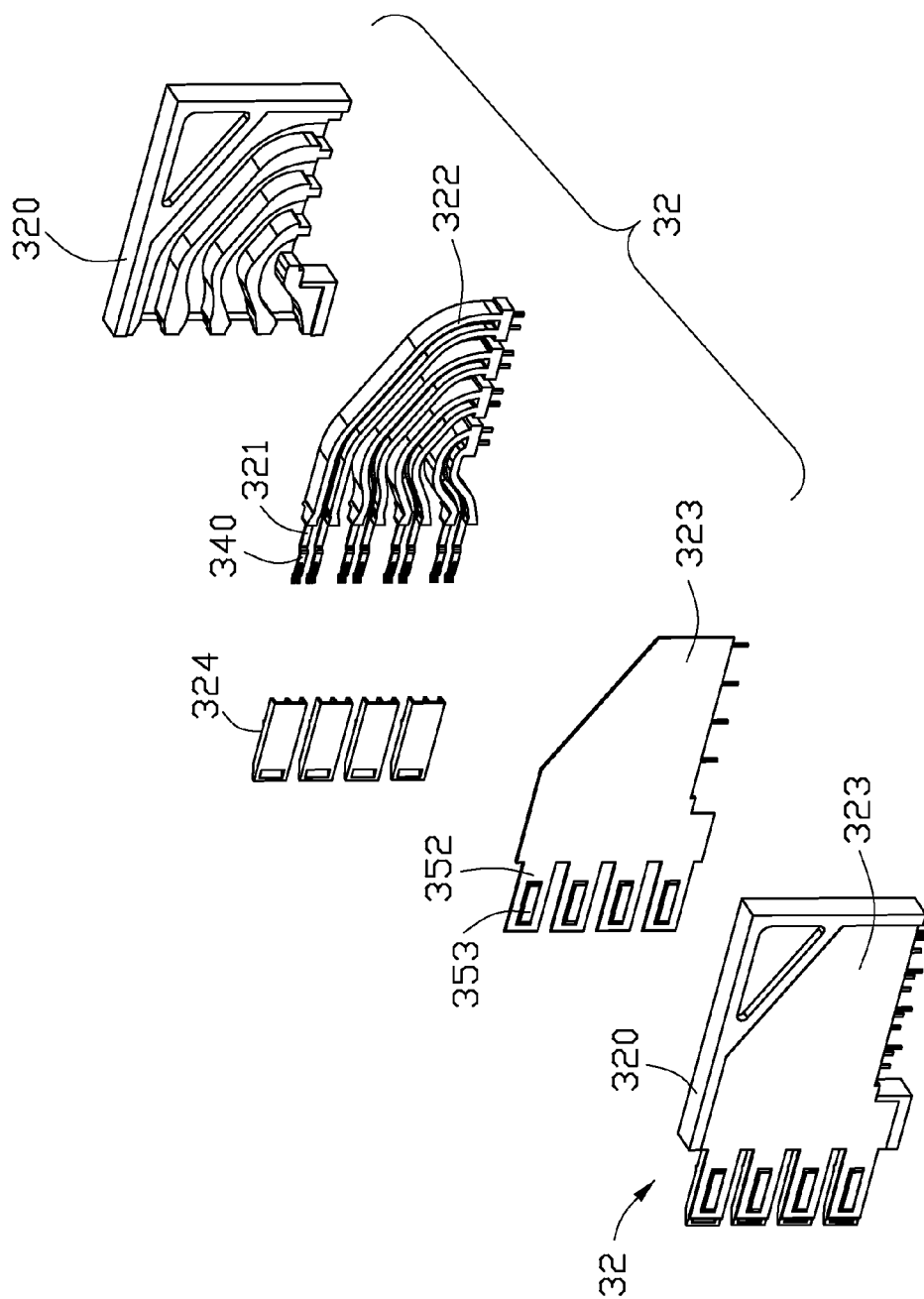


FIG. 2



EIGM





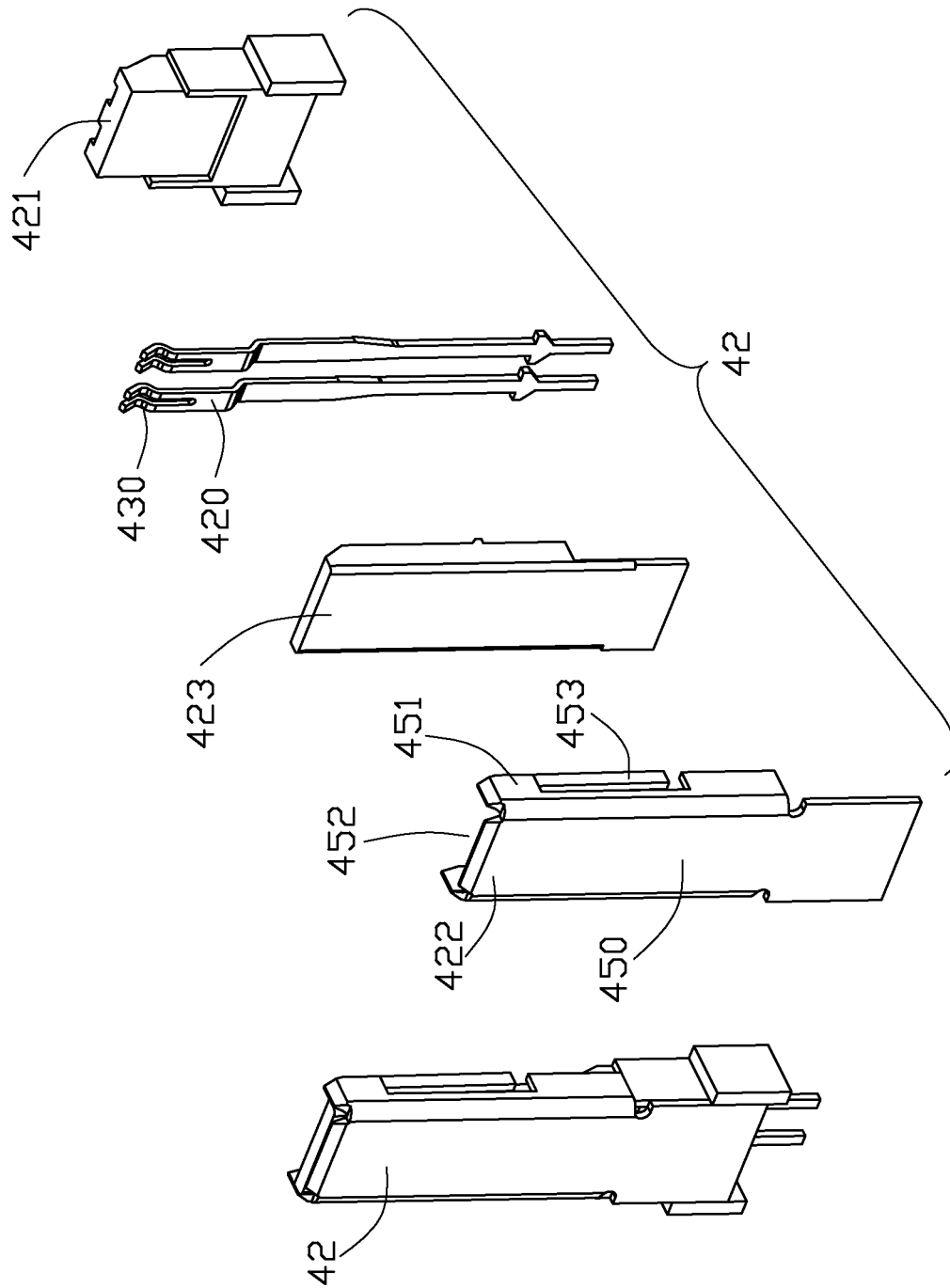


FIG. 6

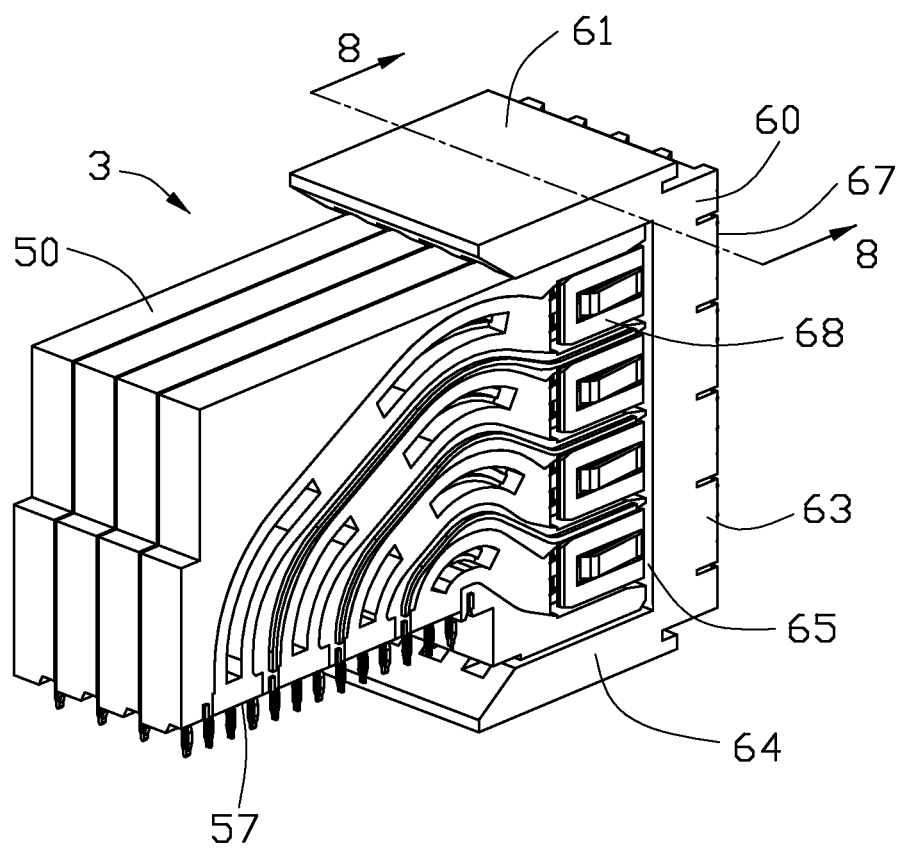


FIG. 7

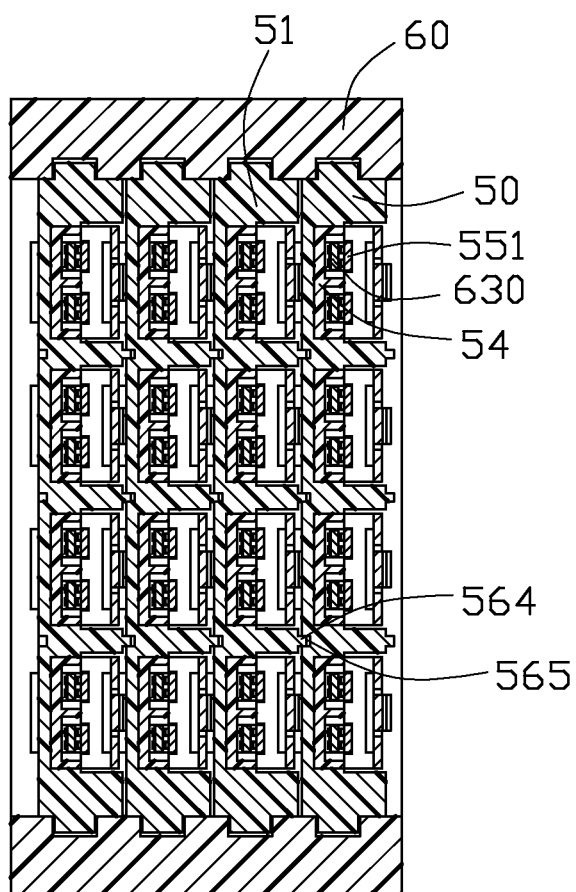


FIG. 8

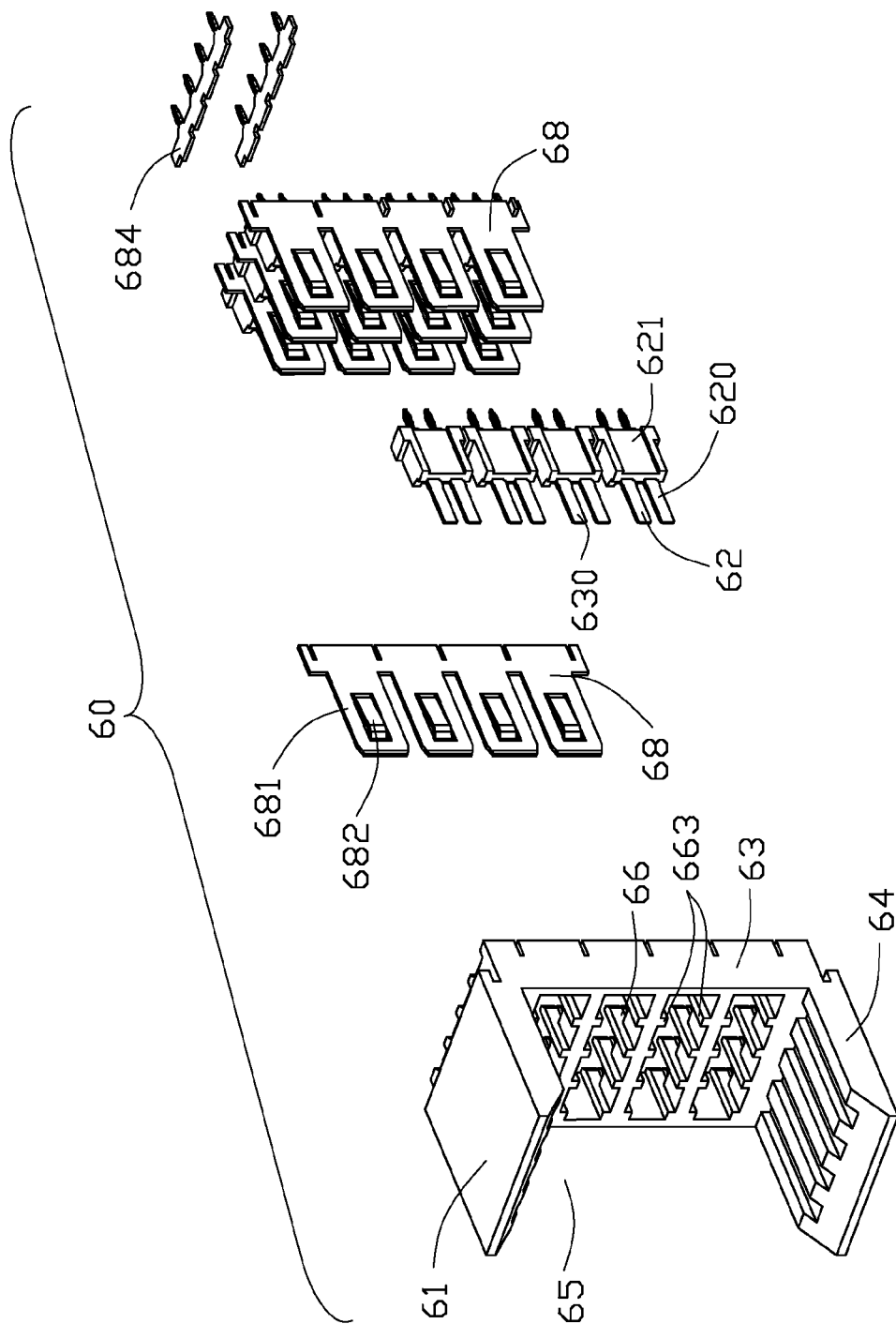


FIG. 9

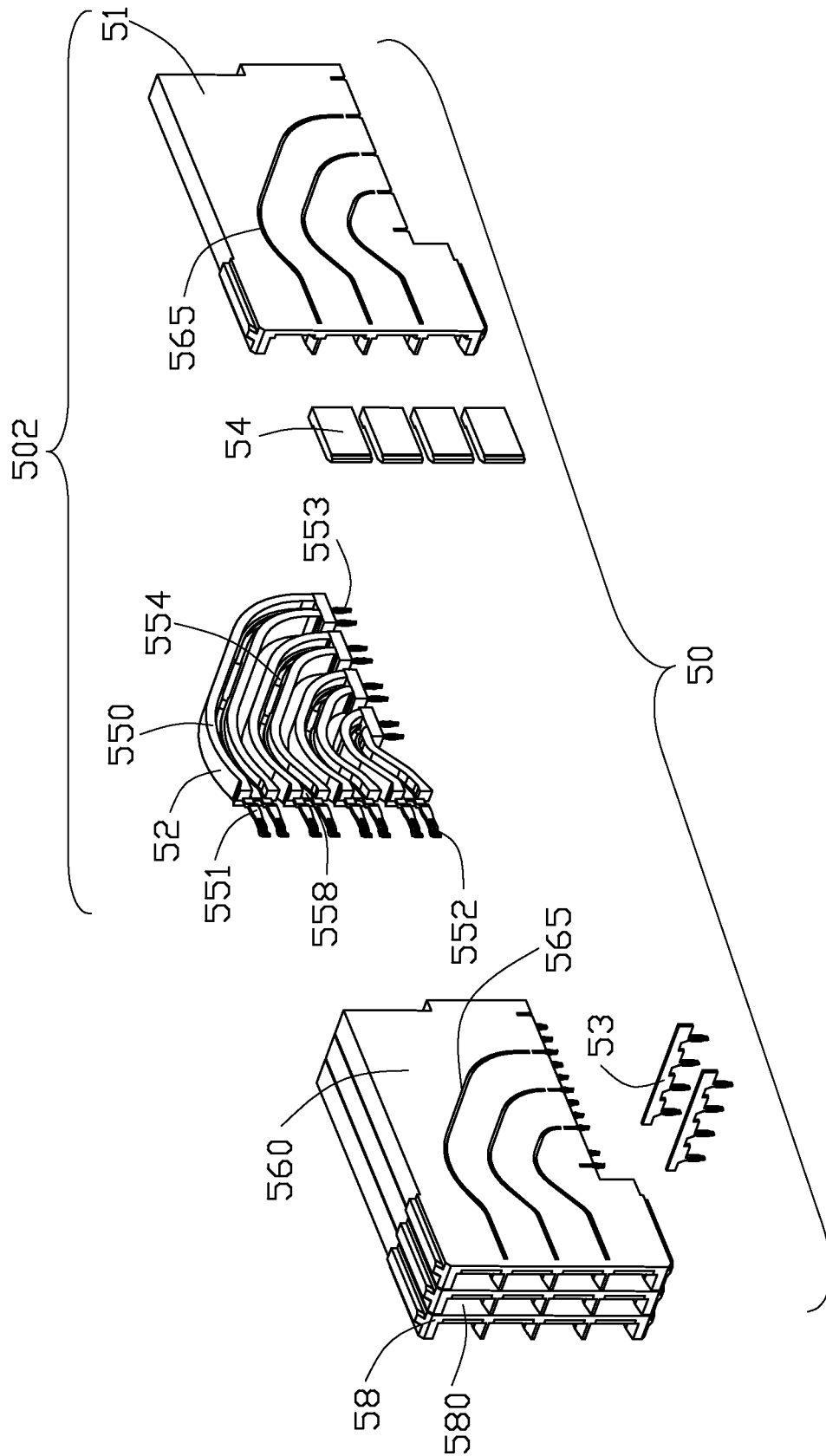


FIG. 10

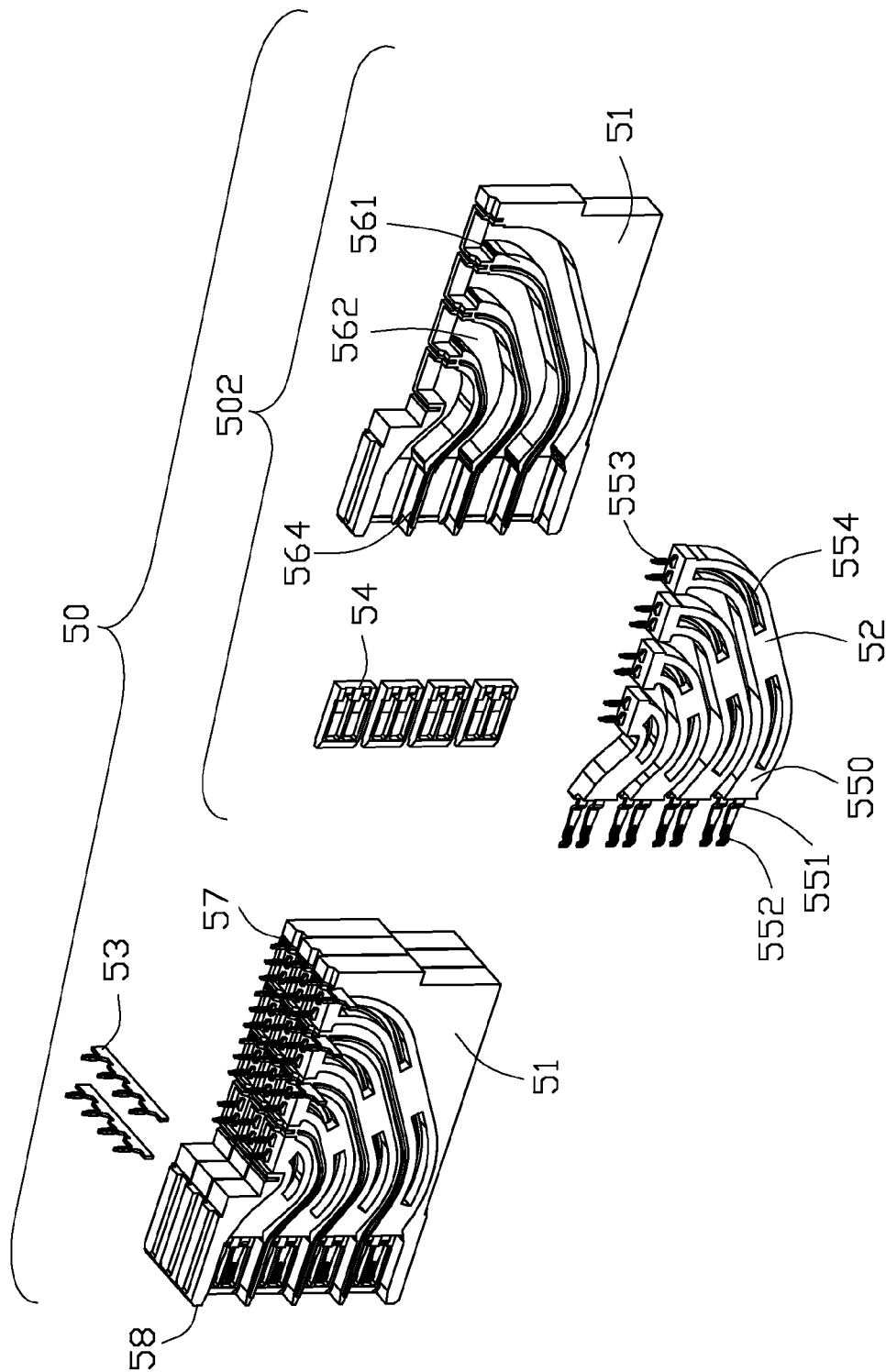


FIG. 11

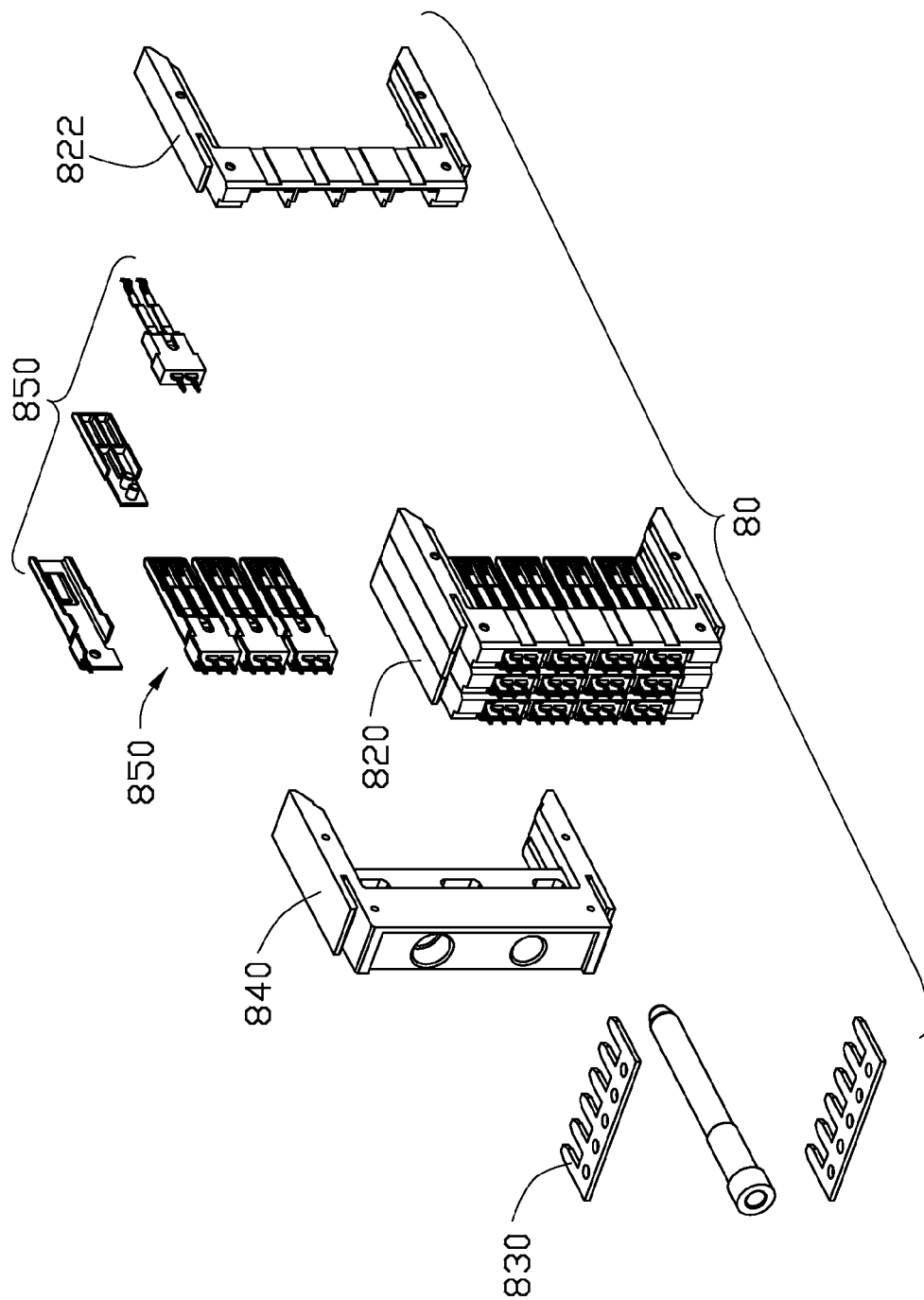


FIG. 12

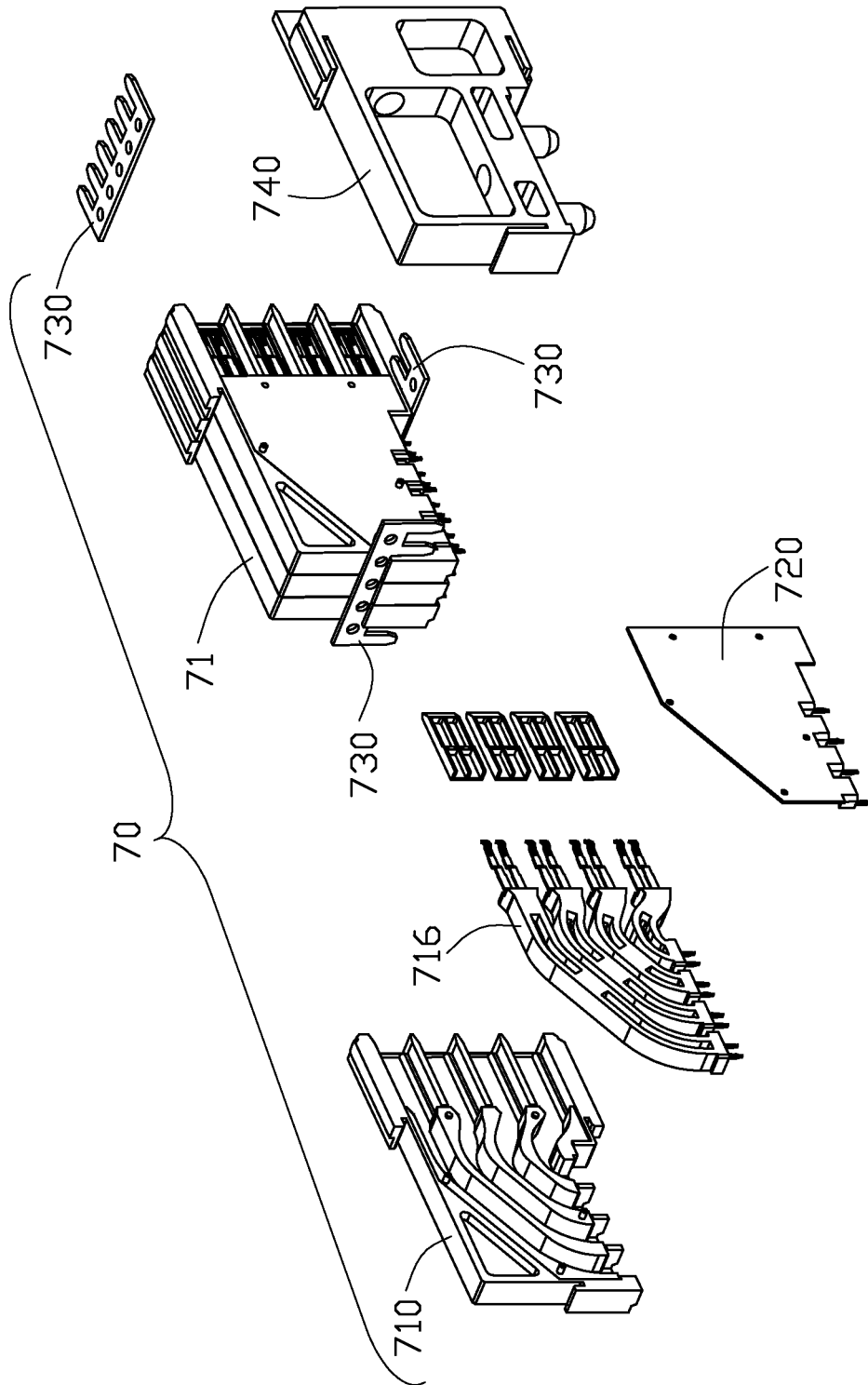


FIG. 13

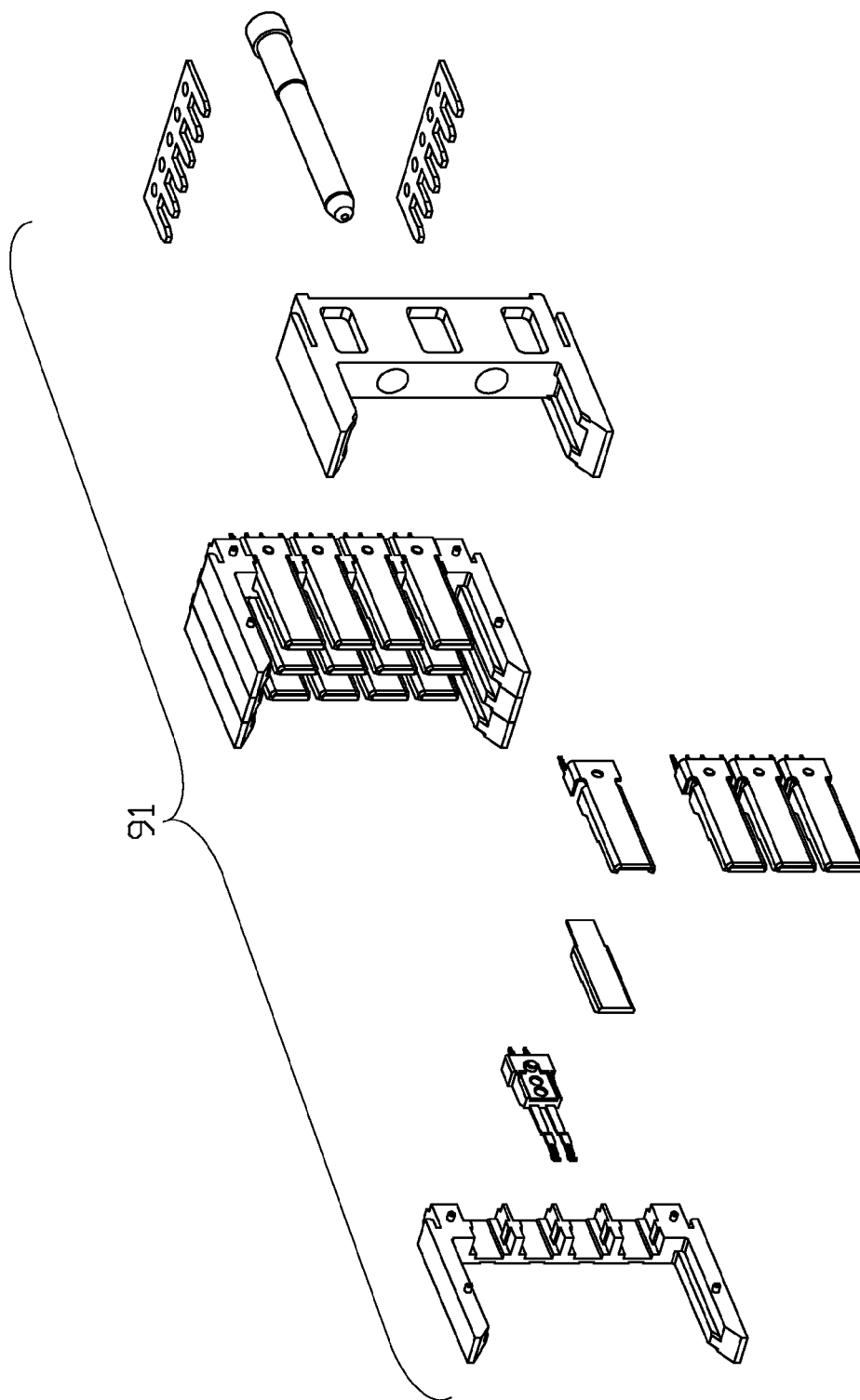


FIG. 14

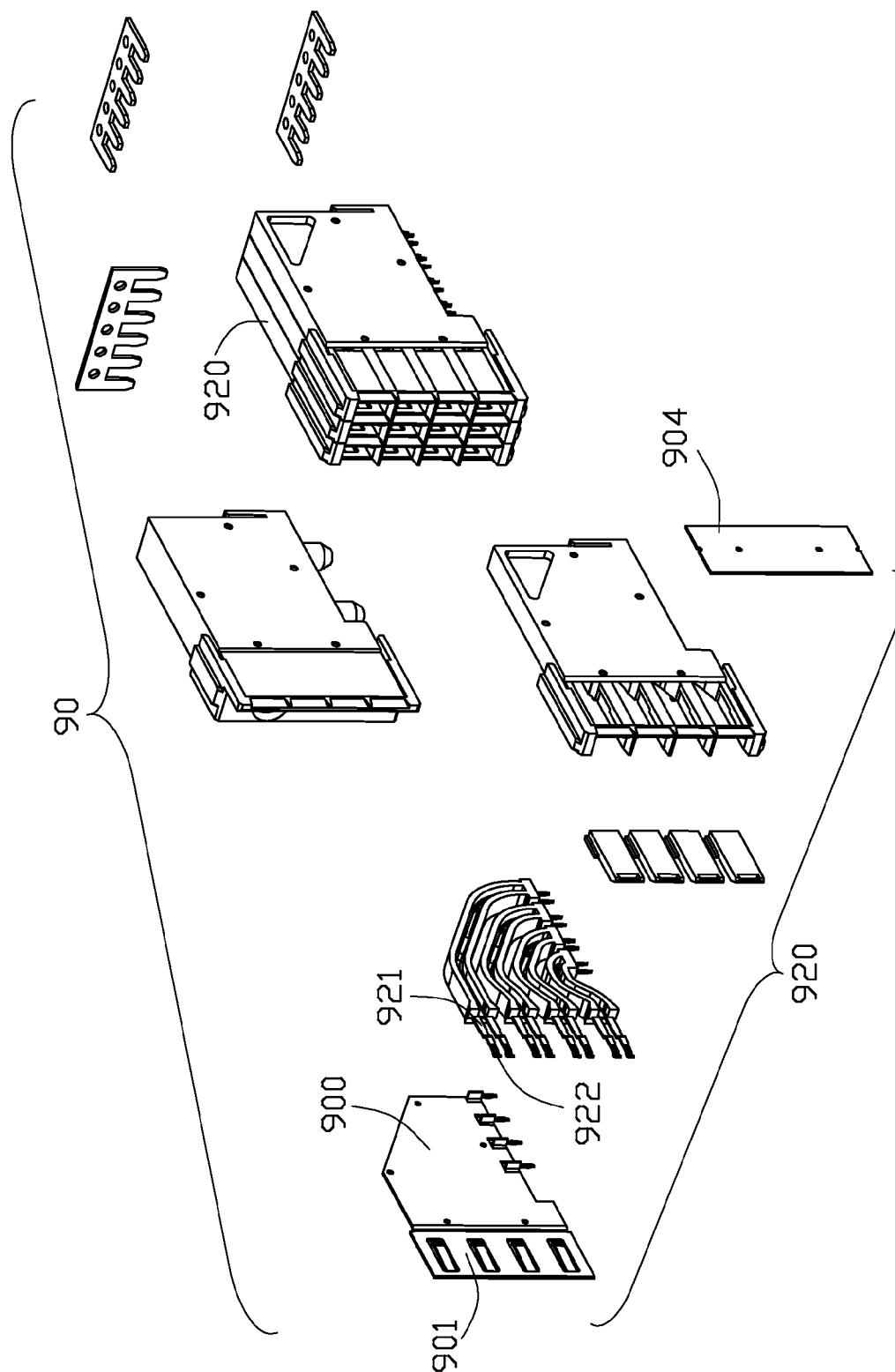


FIG. 15

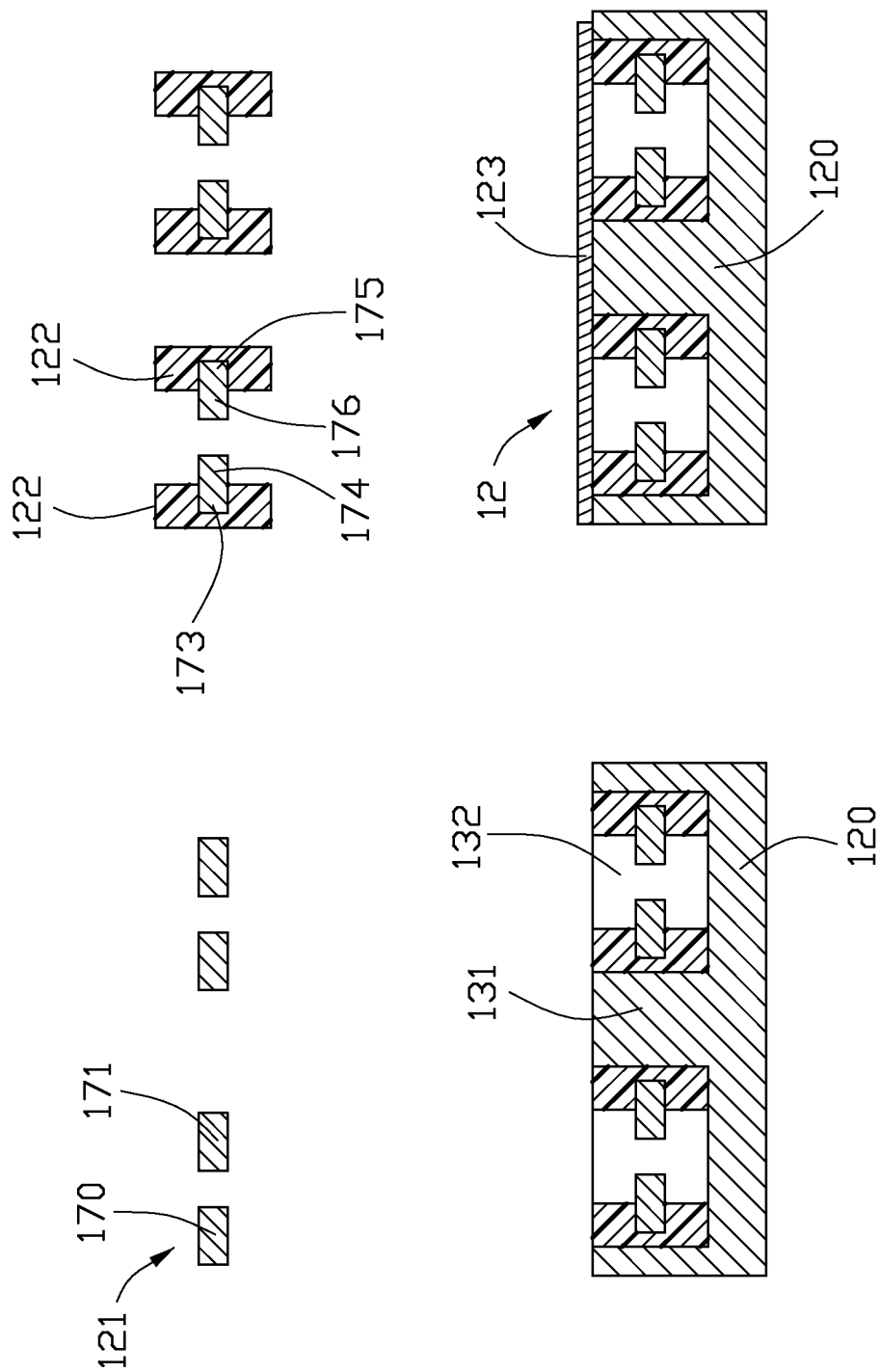


FIG. 16

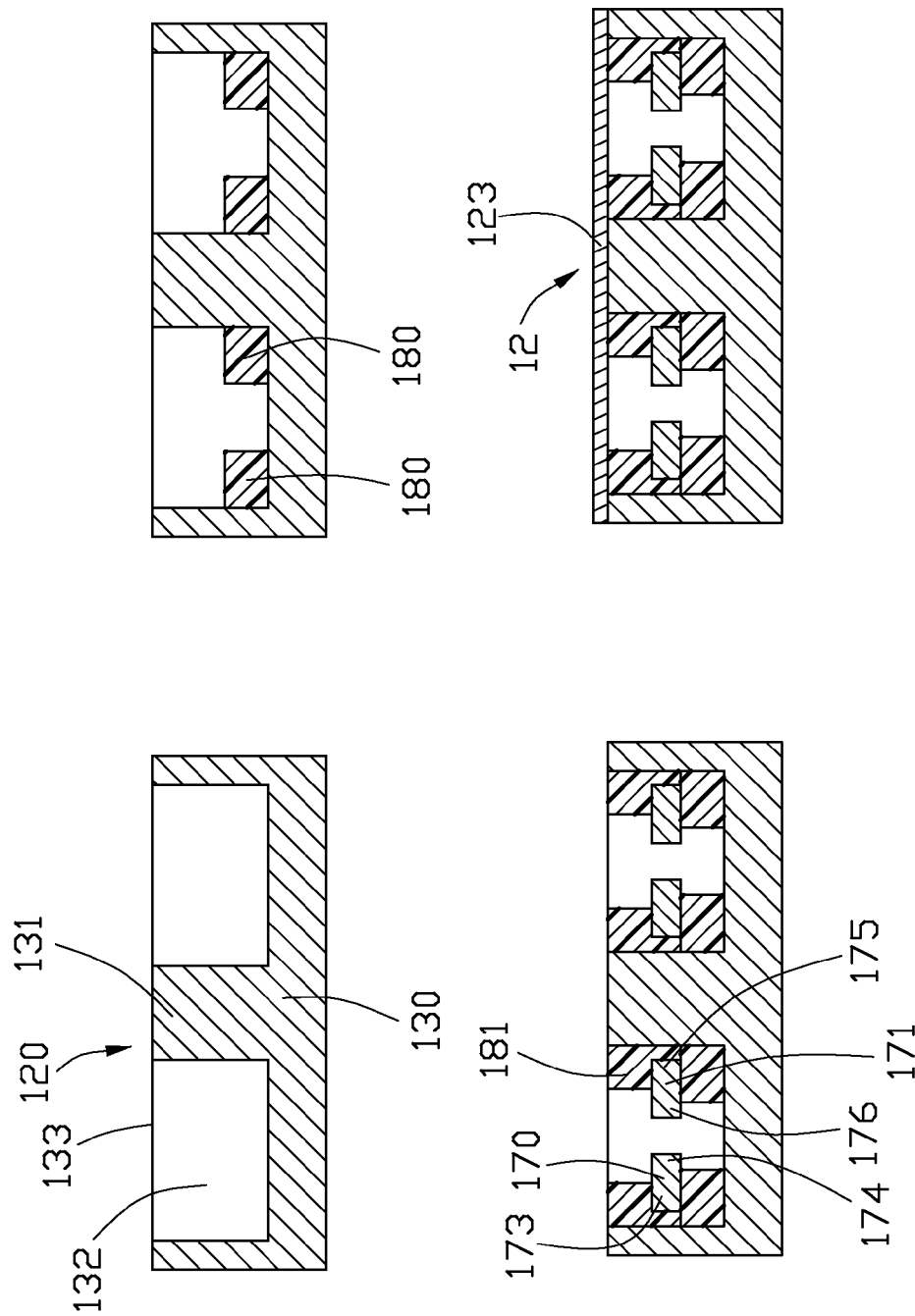


FIG. 17

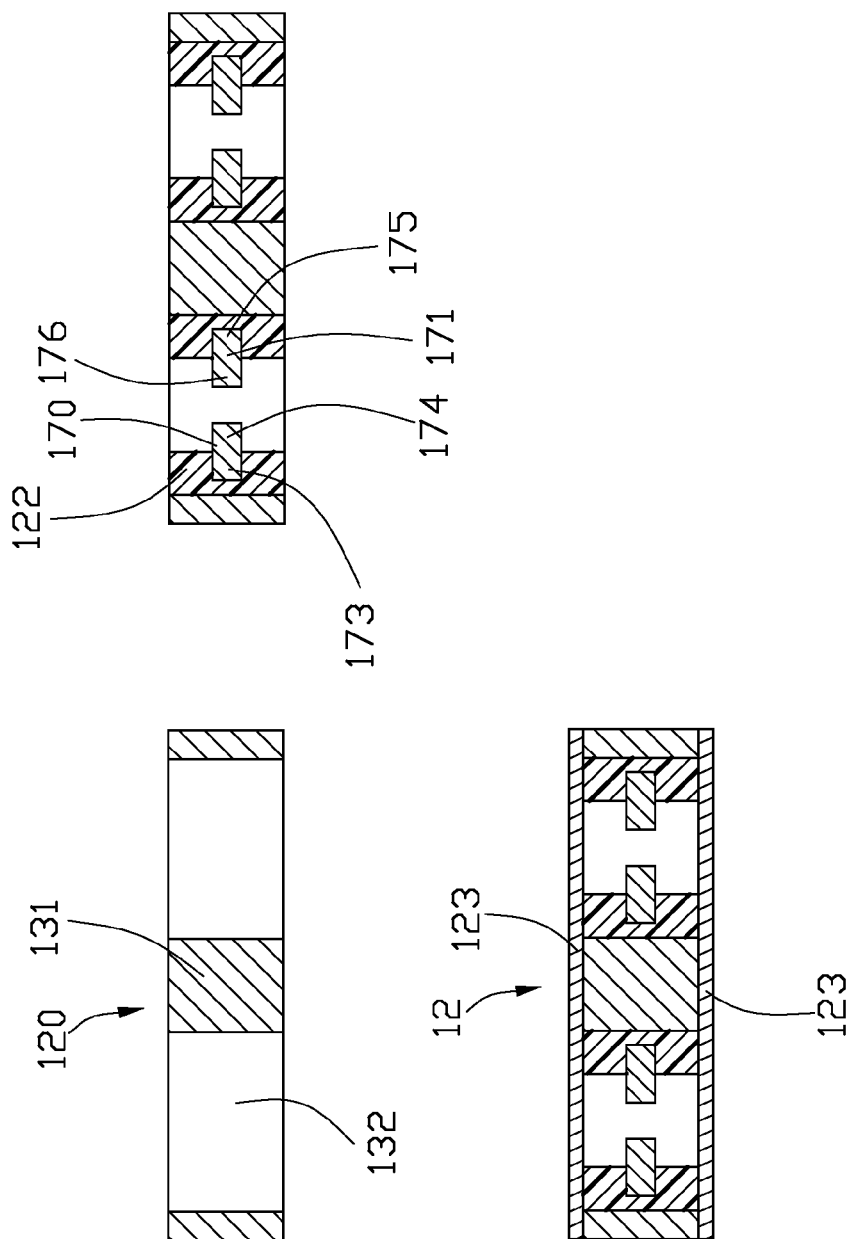


FIG. 18

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HIGH SPEED HIGH DENSITY CONNECTOR ASSEMBLY

CROSS-REFERENCE TO RELATED APPLICATIONS

This patent application is a continuation application of application Ser. No. 13/772,232 filed on Feb. 20, 2013. This patent application is also related to U.S. Pat. No. 8,715,005 B2, issued on May 6, 2014, and entitled "HIGH SPEED HIGH DENSITY CONNECTOR ASSEMBLY," which is assigned to the same assignee as this application. This application further relates to the copending application Ser. Nos. 14/592,855 and 14/592,417.

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention relates to a high speed high density connector assembly, and more particularly, to a high speed high density connector assembly having stacked contact wafers that are completely shielded.

2. Description of the Prior Art

Many prior art references disclose high speed high density connector assemblies with shielding structures. U.S. Pat. No. 6,709,294 B1, issued to Cohen et al. on Mar. 23, 2004, discloses an electrical connector having electrical conductors in a plurality of rows. Each of the plurality of rows includes a housing and a plurality of electrical conductors. Each electrical conductor has a first contact end connectable to a printed circuit board, a second contact end, and an intermediate portion therebetween that is disposed within the housing. The housing includes a first region surrounding each of the plurality of electrical conductors, the first region made of insulative material and extending substantially along the length of the intermediate portion of the electrical conductors. The housing also includes a second region adjacent the first region and extending substantially along the length of the intermediate portion of the electrical conductors. The second region is made of a material with a binder containing conductive fillers providing shielding between signal conductors. Furthermore, in discussing background art in U.S. Pat. No. 6,709,294, it is mentioned that a solution is introduced to provide shields through plastics coated with metals, but there are no combination of readily available and inexpensive metals and plastics that can be used, such as the plastic lacks desired thermal or mechanical properties, available plating techniques are not selective, etc.

U.S. Pat. No. 6,471,549 B1, issued to Lappohn on Oct. 29, 2002, discloses a shielded plug-in connector. The plug-in connector has a jack-in-blade strip having at least one first contact element and an edge connector having at least one second contact element corresponding to the first contact element. The edge connector, on or in its outer body areas, has at least partially shielding sheets. Shielding of the plug-in connector is achieved by, in addition to the shielding sheets provided on the edge connector, a shielding group with at least one first element arranged in the jack-in-blade strip. The first element of the shielding group is a base part in the form of a U-shaped rail. The shielding sheets on the edge connector have a planar body and angled stays. Two of the angled stays and a portion of the planar body between the two angled stays form a counterpart to the base part, wherein the counterpart and the base part together substantially encapsulate the first and second contact elements.

U.S. Pat. No. 7,581,990 B2, issued to Kirk et al. on Sep. 1, 2009, discloses a waferized electrical connector incorporat-

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ing electrically lossy material selectively positioned to reduce crosstalk without undesirably attenuating signals. Wafer may be formed in whole or in part by injection molding of material to form its housing around a wafer strip assembly. A two shot molding operation may be adopted, allowing the housing to be formed of two types of material having different material properties, namely an insulative portion being formed in a first shot and lossy portion being formed in a second shot. The housing may include slots that position air, or create regions of air, adjacent signal conductors in order to provide a mechanism to de-skew a differential pair of signal conductors.

OBJECTS OF THE INVENTION

A main object of the present invention is to provide a high speed high density electrical connector assembly with improved shielding performance.

The present invention first provides an electrical connector comprising a plurality of contact wafers stacked with each other along a transverse direction, each contact wafer comprises a conductive body; one or more shielding members mounted to and electrically connecting with the conductive body; and a plurality of contact modules each including an insulator and a pair of contacts fixed by the insulator, the pair of contacts of each contact module being shielded by the conductive body and the one or more shielding members.

The present invention secondly provides an electrical connector assembly comprising: a first connector adapted to be mounted onto a first printed circuit board, the first connector comprising a plurality of first contact wafers stacked with each other along a transverse direction, each first contact wafer comprising: a first conductive body; a plurality of first contact modules mounted to the first conductive body, the first contact modules arranged in columns and rows, each of the first contact modules comprising a first insulator and a pair of first contacts fixed by the first insulator; and a plurality of first shielding members mounted to the first conductive body and electrically connecting with the first conductive body; a second connector adapted to be mounted onto a second printed circuit board and adapted for being mated with the first electrical connector, the second connector comprising: a second conductive body comprising a mounting wall (23; 63) for being mounted to the second printed circuit board, a pair of side walls (24; 64) extending from opposite sides of the mounting wall, and a receiving room (25; 65) formed by the mounting wall and the side walls, a portion of the first conductive body received into the receiving room and electrically connecting with the second conductive body; a plurality of second contact modules mounted to the second conductive body, the second contact modules arranged in columns and rows, each of the second contact modules comprising a second insulator (221; 421; 621) and a pair of second contacts (220; 420; 620) fixed by the second insulator; and a plurality of second shielding members (222; 422; 68) mounted to the second conductive body.

BRIEF DESCRIPTION OF THE DRAWINGS

The features of this invention which are believed to be novel are set forth with particularity in the appended claims. The invention, together with its objects and the advantages thereof, may be best understood by reference to the following description taken in conjunction with the accompanying drawings, in which like reference numerals identify like elements in the figures and in which:

FIG. 1 is a perspective view of a connector assembly of according to a first embodiment of the present invention;

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FIG. 2 is a cross-section view of the electrical connector system when cut in a line II-II shown in FIG. 1;

FIG. 3 is a perspective view of the stacked contact wafers with one contact wafer being exposed shown in FIG. 1;

FIG. 4 is a perspective view of two contact modules shown in FIG. 1, one in assembled condition and the other in exposed condition;

FIG. 5 showing two contact wafers of a plug according to a second embodiment of the present invention, one in assembled condition and the other in exposed condition;

FIG. 6 showing two contact modules of a header according to a second embodiment of the present invention, one in assembled condition and the other in exposed condition;

FIG. 7 is a perspective view of a connector assembly of according to a third embodiment of the present invention;

FIG. 8 is a cross-section view of the electrical connector system when cut in the line VIII-VIII shown in FIG. 7;

FIG. 9 is a partially exploded view of a header shown in FIG. 7;

FIG. 10 is a partially exploded view of a plug shown in FIG. 7;

FIG. 11 is another partially exploded view of the plug shown in FIG. 7 in a different viewpoint;

FIG. 12 is a partially exploded view of a header of a connector assembly according to a fourth embodiment of the present invention;

FIG. 13 is a partially exploded view of a plug of a connector assembly according to the fourth embodiment of the present invention;

FIG. 14 is a partially exploded view of a header of a connector assembly according to a fifth embodiment of the present invention;

FIG. 15 is a partially exploded view of a plug of a connector assembly according to the fifth embodiment of the present invention;

FIG. 16 showing a first method of making the contact wafer shown in FIG. 1;

FIG. 17 showing a second method of making the contact wafer shown in FIG. 1; and

FIG. 18 showing a third method of making the contact wafer shown in FIG. 1.

DETAILED DESCRIPTION OF THE INVENTION

Reference will now be made to the drawing figures to describe the present invention in detail.

FIGS. 1-4 show a connector assembly according to a first embodiment of present invention. The connector assembly 1 is shown to connect a daughter card (not shown) to a backplane (not shown). The connector assembly 1 includes a plug 10 mounted onto the daughter card and a header 20 mounted onto the backplane.

The plug 10 includes a conductive front housing 11 and a number of contact wafers 12 stacked along a transverse direction and mounted to a rear face of the front housing 11. The plug 10 defines a mounting face 17 adapted to be mounted onto the daughter card. The header 20 includes a mounting face 27 adapted to be mounted onto the backplane.

The front housing 11 is made from die casting metal or conductive plastic, or insulating piece plated with metal plating. In a preferred embodiment, the front housing 11 is made from thermoplastic plated with metal plating, such as Chromium, Copper, Tin and Gold. The front housing 11 defines a front face 13 forwardly facing the header 20, a rear face 14 opposite to the front face 13 and a number of holes 15 extending through the rear face 14 and the front face 13.

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Each of the wafers 12 includes a conductive board 120 defining mutual opposite first face and second face, four pairs of first signal contacts 121, four first insulating holders 122 respectively fixing the pairs of first signal contacts 121, a first shielding plate 123, and four first insulating protectors 124 assembled to the conductive board 120. Each pair of first signal contacts 121 are insert-molded with one corresponding first insulating holder 122 to form a contact module (not labeled), and thus there are four contact modules in each wafer 12 in each wafer 12. The first shielding plate 123 has a planar portion 150 and eight grounding feet 151 extending downwardly from the planar portion 150. The conductive board 120 is electrically connected to the first shielding plate 123 and connected to the daughter card through grounding feet 151 of the first shielding plate 123. The metal shielding plate 123 is added to keep the insulating holders 122 from being extruding out from the conductive board 120 when the plug 10 is mounted onto the daughter card and further improve shielding performance.

The conductive board 120 defines four slots 132 in the first face respectively receiving corresponding contact modules and three isolating walls 131. Each of the first contacts 121 includes a deflectable contacting portion 140 received in the front housing 11, a foot portion 141 extending out from the conductive board 120, and an intermediate portion 142 connecting the contacting portion 140 and the foot portion 141. Differential signals are transferred in the contact pair 121 in each slot 132 of the conductive board 120.

The conductive board 120 is made from die casting metal or conductive plastic, or insulating piece plated with a metal plating. In a preferred embodiment, the conductive board 120 is made from thermoplastic with a high melt point above 300 degrees Celsius, and plated with metal plating such as Chromium, Copper, Tin and Gold. Comparing to the second region made of a material with a binder containing conductive fillers to provide shielding between signal conductors, which disclosed in U.S. Pat. No. 6,709,294 B1 by Cohen et al. on Mar. 23, 2004, the plated conductive board 120 in present invention more perfectly provides shielding between adjacent wafers 12 and decreases crosstalk between adjacent contact pairs 121 received in the same wafer 12. Further more, the contact modules are inserted into the slots 132 of the conductive board 120, so there is no need to insert-mold the first insulating holders 122 into the slots 132 of the conductive board 120, which decreases potential risk of destroying the metal plating of the conductive board 120.

Each of the first insulating protector 124 includes a base board 126, a pair of side walls 161, an intermediate wall 162, and a pair of cavities 163 for receiving the contacting portions 140 of corresponding pair of first contacts 121. The first insulating protectors 124 has front ends received in the front housing 11 and rear ends received in the conductive boards 120. The cavities 163 of the insulating protectors 124 and the slots 132 open to a same side in the transverse direction. The contacting portion 140 is sheltered by the first insulating protector 124 such that the contacting portion 140 is deflectable only in the transverse direction away from the first shielding plate 123 towards the conductive board 120.

The header 20 includes a conductive shroud 21 and a number of contact modules 22 arrayed in the conductive shroud 21. The conductive shroud 21 is made from die casting metal or conductive plastic, or insulating piece plated with metal plating. In a preferred embodiment, the conductive shroud 21 is made from thermoplastic, and plated with metal plating such as Chromium, Copper, Tin and Gold. The shroud 21 includes a bottom wall 23, two upwardly extending side walls 24 and a receiving space 25 defined therebetween for receiving

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ing a portion of the plug 10. The bottom wall 23 defines an array of holes 26 each receiving one of the second contact modules 22.

Each of the contact module 22 includes a pair of second contacts 220, a second insulating holder 221 insert-molded with the pair of second contacts 220, a second shielding plate 222 assembled to the second insulating holder 221, and a second insulating protector 223. The second insulating holder 221 and the second insulating protector 223 are used to fix the pair of second contacts 220 and keep them isolated from the second shield 222.

Each of the second contacts 220 includes a deflectable contacting portion 230 inserted into corresponding holes 15 of the plug 10, a foot portion 231 extending downwardly for mounting onto the backplane, and an intermediate portion 232 connecting the contacting portion 230 to the foot portion 231. The intermediate portion 232 is embedded in the second insulating holder 221 and isolated from the conductive shroud 21.

Each second insulating holder 221 of the header 20 defines two positioning holes 240. The second shielding plate 222 including a planar board portion 250, a pair of ground feet 251, and a flexible contacting arm 252 punched from the board portion 250 and extending towards the ground feet 251. The second insulating protector 223 forms a pair of positioning posts 260 interference fitting with the two position holes 240 of the second insulating holder 221. The conductive shroud 21 is electrically connected to the second shielding plates 222 and further electrically connected to the backplane through the grounding feet 251 of the second shielding plates 222.

It should be understandable that when the plug 10 is mated with the header 20, the conductive boards 120 make electrical connection with the conductive shroud 21, and the contacting portions 252 of the second shielding plates 222 contact the front housing 11 of the plug 10. It should be also understandable that the signal routing path, which extends from the foot portions 231 of the second contacts 220 to the foot portions 141 of the first contacts 121, is completed shielded in all direction perpendicular to the signal routing path. Furthermore, the filling degree of the insulating holders 122 in one of the slots 132 varies along the signal path in such manner that the pair of the first contacts 121 are fixed to the conductive board 120 by two or three parts 145, 147, 148 of the insulating holders 122 along part lengths of the signal path, and part 146 of the first contacts 121 along part lengths of the signal path is exposed to the air.

Referring to FIGS. 5 and 6, an electrical connector assembly 2 according to a second embodiment of the present invention is shown. The electrical assembly 2 has a plug (not shown) and a header (not shown) similar to the electrical connector assembly 1 except contact wafers 32 of the plug and the contact modules 42 of the header. Each of the contact wafers 32 has a conductive board 320, four pairs of third contacts 321, four third insulating holders 322, four third insulating protectors 360, and a third shielding plate 323. A first difference for the contact wafer 32 is that the shielding plate 323 has four flat tab portions 352 forwardly extending beyond a front edge of the conductive board 320, and each of the tab portions 352 forming a flexible contacting arm 353. A second difference for the contact wafer 32 is that the third insulating protectors 324 are disposed between the contacting portions 340 and the tab portions 352, and the third contacts 321 have contacting portions 340 deflectable in the transverse direction towards the tab portions 352 of the third shielding plate 323. Each of the fourth contact modules 42 has a fourth shielding plate 422, a fourth insulating protector 423, a pair of

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fourth contacts 420, a fourth insulating holder 421. The main difference for the contact module 42 is that the fourth shielding plate 422 has a board portion 450, two side walls 451 to define a U-shaped receiving slot 452 therebetween, and two flexible contacting arms 453 in the two side walls 451, and the fourth insulating protector 423 is secured in the U-shaped slot 452 to isolate contacting portions 430 of the fourth contacts 420 from the fourth shielding plate 422.

Referring to FIGS. 7-11, an electrical connector assembly 3 according to a third embodiment of present invention is shown. The electrical connector assembly 3 has a plug 50 and header 60 similar to the first embodiment. The plug 50 includes a number of contact modules 502 stacked in a transverse direction and five grounding belts 53 connecting the contact modules 502. Each of the contact modules 502 comprises a conductive board 51, four contact modules 52 each having a pair of fifth contacts 551 and a fifth insulating holder 550 insert-molded with the pair of contacts 551, and four insulating protectors 54. Each of the conductive boards 51 defines a first face with a plurality of slots 562 defined therein and an opposite second face with three slits 565 defined therein. The conductive board 51 has three inner walls 561 and three ribs 564. Each of the inner walls 561 is located between every two adjacent slots and each of the ribs 564 protruding from one of the inner walls 561. The contact modules 52 are received in respective slot 562.

When the contact modules 502 are transversely stacked, the ribs 564 mate into corresponding slits 565 of an adjacent contact module 502 to make complete shielding between adjacent fifth contact pairs 551, and the conductive boards 51 jointly define a mounting face 57 to be mounted onto a daughter card (not shown), and a front face 58. The front face 58 forms a plurality of holes 580 therein to receive contacts 620 of the complimentary header 60. Each of the holes 580 formed by one slot 562 of said conductive board 51 and an adjacent conductive board 51.

Each of the fifth contacts 551 has a foot 553, a deflectable contacting portion 552 and an intermediate portion 554 connecting the foot 553 and the contacting portion 551. The contacting portions 552 and the intermediate portions 554 of each contact pair 551 are received in corresponding slot 562, and the feet 553 extending perpendicularly from the mounting face 57.

Each of the insulating protectors 54 is received in the holes 580 and between the contacting portions 552 of corresponding pairs of fifth contacts 551 and the bottom wall of corresponding slot 562. The contacting portions 552 are deflectable in the transverse direction towards the bottom wall of corresponding slot 562 and front ends of the contacting portion 552 are sheltered by the insulating protector 54. The main difference for the header 50 comparing the header 10 of the first embodiment is that there is no conductive housing 11 and no first shielding plate 123.

Jointly referring to FIGS. 10 and 11, similar to the first embodiment, the filling degree of the fifth insulating holders 550 in one of the slots 562 varies along the signal path in such manner that the pair of the first contacts 551 are fixed to the conductive board 51 by one of the fifth insulating holders 550 along part lengths of the signal path, and at least part of the first contacts 551 along part lengths of the path is exposed to the air. It is further shown that the part of insulating holder 52 near the contacting portion 552 defines a slot 558 to change the dielectric disposed around the fifth contact pair 551, which make the impedance to the signal in the fifth contact pair 551 approaching a constant along the signal path.

Referring to FIGS. 7-9, the header 60 includes a conductive shroud 61, sixteen pairs of sixth contact modules 62, four

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sixth shielding plates **68**, and five grounding belts **684**. Each of the sixth shielding plates **68** has four flat tabs **681** and four flexible contacting arms **682**. Each of the sixth contact modules **62** includes an insulating holder **621** and a pair of sixth contacts **620**. Each of the sixth contacts **620** has a non-deflectable contacting portion **630**. The conductive shroud **61** includes a bottom wall **63**, two upwardly extending side walls **64** and a receiving space **65** defined therebetween for receiving a portion of the plug **50**. The bottom wall **63** of the conductive housing **61** defines four through holes **66** each having pairs of ribs **663** protruding from opposite inner faces of the holes **66**, the pairs of ribs **663** dividing each of the holes **66** into four receiving spaces to receive one of the contact modules **62** and corresponding tab **681** of the shielding plates **68**.

The differences for the header **60** comparing to the first embodiment is listed as below: (1) there is no insulating protector between the tabs **681** of the shielding plates **68** and the contacting portions **630**, which improve the impedance of the contact pair; (2) each hole **66** of the shroud **61** receive four sixth contact modules **62** and corresponding flat tabs **681** stacked in a column direction; (3) four flat tabs **681** corresponding to each contact module **62** are integrally formed in the sixth shielding plate **68** extending in a row direction; (4) there are grounding belts **684** extending along the column direction and connecting the sixth shielding plate **68** and the conductive shroud **61** to the backplane.

Referring to FIGS. **12-13**, a connector assembly according to a fourth embodiment is shown. The connector assembly includes a plug **70** and a header **80**. The header **80** includes four contact wafers **820** and a guide wafer **840** stacked in a transverse direction, and two sawtooth organizers **830** latching opposite sides of the wafers **820**, **840**. Each of the contact wafers **820** includes a conductive board **822** and four contact modules **850**. Each of the contact modules **850** has similar structure to aforementioned contact module **42**. The plug **70** includes four contact wafers **71** and one guide wafer **740** stacked in a transverse direction, and three organizers **730** latching the wafers **71**, **740**. The metal shielding plate **720** is added to keep the contact module **716** from being extruding out from the conductive board **710** when the plug **70** is mounted onto the daughter card and further improve shielding performance.

Referring to FIGS. **14-15**, a connector assembly according to a fifth embodiment is shown. The connector assembly includes a plug **90** and a header **91**. The header **91** has similar structure to the aforementioned header **80**. The plug **90** has similar structure to the aforementioned plug **70** except that each contact wafer **920** adds two contacting plates **901**, **904** extending across four pairs of contacts **921** aside the contacting portions **922** to improve shielding performance and mating durability, wherein the contacting plate **901** is integral with a shielding plate **900** covering aside the contact wafer **920**.

Referring to FIG. **16**, a method for making the contact wafer **12** of the plug **10** is shown. The method includes the following steps: (1) punching a metal strip to form a contact pair **121** including a left contact **170** and a right contact **171**, the left contact **170** and the right contact **171** being carried in a planar in an edge-to-edge manner; (2) insert-molding the contact pair **121** into an insulating holder **122** with a left edge **173** of the left contact **170** and a right edge **175** of the right contact **171** embedded in the insulating holder **122**, and a right edge **174** of the left contact **170** and a left edge **176** of the right contact **171** exposed to air; (3) assembling the contact module formed in step (2) into a slot **132** of a conductive board **120**; (4) covering a shielding plate **123** over a side of the

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conductive board **120**. Jointly referring to FIG. **3**, it could also be described that each pair of contacts **170**, **171** are kept in a planar surface with near edges **174**, **176** facing to each other and far edges **173**, **175** backing away from each other, the far edges **173**, **175** of the intermediate portions embedded in the first insulating holder **122** and the near edges **174**, **176** of the intermediate portions exposed to air in part length of the signal path, which make the pair of contacts **170**, **171** firmly fixed by the first insulating holders **122**, and at the same time there is void between the near edges **174**, **176** to improve the impedance of the contact pair **170**, **171**.

Referring to FIG. **17**, a second method for making the contact wafer **12** is shown. The method includes the following steps: (1) providing a conductive board **130** having slots **132** therein; (2) insert-molding a first plastic **180** on a bottom wall of the slot **132**; (3) putting a contact pair **170**, **171** punched from a metal strip into the slot **132** and on the first plastic **180**, and insert-molding a second plastic **181** in the slot **132** on the first plastic **180** and the contact pair **170**, **171**; (4) covering a shielding plate **123** over a side of the conductive board **120**.

Referring to FIG. **18**, a third method for making an alternative contact wafer **12** is shown. The method includes the following steps: (1) providing a conductive board **130** having through holes **132** therein; (2) insert-molding a contact pair **170**, **171** and an insulating holder **122** into the through holes **132** with near edges **174**, **176** exposed to air and far edges **173**, **175** embedded in the insulating holder **122**; (3) covering two metal plate **123** over opposite sides of the conductive board **120**.

It is to be understood, however, that even though numerous, characteristics and advantages of the present invention have been set forth in the foregoing description, together with details of the structure and function of the invention, the disclosed is illustrative only, and changes may be made in detail, especially in matters of number, shape, size, and arrangement of parts within the principles of the invention to the full extent indicated by the broad general meaning of the terms in which the appended claims are expressed.

What is claimed is:

1. An electrical connector comprising a plurality of contact wafers stacked with each other along a transverse direction, each contact wafer comprising:

a conductive body;

one or more shielding members mounted to and electrically connecting with the conductive body;

a plurality of contact modules each including an insulator and a pair of contacts fixed by the insulator, the pair of contacts of each contact module being shielded by the conductive body and the one or more shielding members; and

a plurality of protectors for insulating the contacts from the conductive body.

2. An electrical connector as claimed in claim 1, wherein the conductive body comprises a flat base portion, a plurality of ribs vertically extending from a side of the flat base portion, and a plurality of receiving portions formed by every two adjacent ribs and the flat base portion, the receiving portion defining an opening for the contacts to enter into.

3. An electrical connector as claimed in claim 2, wherein the shielding member is mounted on the conductive body and sealed with the openings of the receiving portions.

4. An electrical connector as claimed in claim 1, further comprising a plurality of organizers to mechanically fix the conductive bodies together.

5. An electrical connector assembly comprising:

a first connector adapted to be mounted onto a first printed circuit board, the first connector comprising a plurality

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of first contact wafers stacked with each other along a transverse direction, each first contact wafer comprising:

- a first conductive body;
- a plurality of first contact modules mounted to the first conductive body, the first contact modules arranged in columns and rows, each of the first contact modules comprising a first insulator and a pair of first contacts fixed by the first insulator; and
- a plurality of first shielding members mounted to the first conductive body and electrically connecting with the first conductive body;
- a second connector adapted to be mounted onto a second printed circuit board and adapted for being mated with the first electrical connector, the second connector comprising:
 - a second conductive body comprising a mounting wall for being mounted to the second printed circuit board, a pair of side walls extending from opposite sides of the mounting wall, and a receiving room formed by the mounting wall and the side walls, a portion of the first conductive body received into the receiving room and electrically connecting with the second conductive body;
 - a plurality of second contact modules mounted to the second conductive body, the second contact modules arranged in columns and rows, each of the second contact modules comprising a second insulator and a pair of second contacts fixed by the second insulator; and
 - a plurality of second shielding members mounted to the second conductive body.

6. An electrical connector assembly as claimed in claim 5, wherein each of the first conductive bodies comprises a flat base portion, a plurality of ribs vertically extending from a side of the flat base portion, and a plurality receiving portions formed by adjacent ribs and the flat base portion, the receiving portion defining an opening for entering the first contacts.

7. An electrical connector assembly as claimed in claim 6, wherein each of the first contacts comprises a first mounting portion extending downwardly beyond the first conductive body, a first mating portion received in the first conductive body and for being mated with the second contact, and a first connecting portion connecting with the first mounting portion and the first mating portion, the first connector comprising a plurality of spacers received into the receiving portions for insulating the first contact portions from the first conductive bodies.

8. An electrical connector assembly as claimed in claim 7, wherein each of the first shielding members is mounted on a corresponding one of the first conductive bodies and sealed with the openings of the receiving portions.

9. An electrical connector assembly as claimed in claim 8, wherein each of the first shielding members comprises first contacting portion disposed at a side of a corresponding first mating portion and electrically connects with the second shielding member.

10. An electrical connector assembly as claimed in claim 5, wherein each of the first shielding members extends along the transverse direction and electrically connects with at least two of the first conductive bodies, each of the first shielding mem-

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bers comprising a plurality of first mounting legs for being mounted to the first printed circuit board.

11. An electrical connector assembly as claimed in claim 5, wherein each of the second shielding members comprises a base portion and a plurality of second contacting portions extending from the base portion.

12. An electrical connector assembly as claimed in claim 5, wherein the first connector comprises a plurality of organizers to mechanically fix the first conductive bodies together.

13. An electrical connector assembly as claimed in claim 5, wherein the second conductive body comprises a plurality of second conductive members electrically and mechanically connected with each other, the second contact modules and the second shielding members mounted to the second conductive members, respectively, the second shielding members electrically connecting with the second conductive wafers.

14. An electrical connector assembly comprising:

a first electrical connector including a first conductive body forming a receiving space therein;

a plurality of contact modules disposed in the first conductive body in matrix arranged with rows and columns, each of said contact module including a pair of differential contacts embedded within an insulator with legs for mounting to a printed circuit board on which the first conductive body is seated, means for shielding each of said contact module along a row direction and a column direction perpendicular to each other; wherein

said means is electrically and mechanically connected to the first conductive body;

each of said contact modules defines a rectangular cross-section, and said means includes a first metallic shielding plate extending along the row direction to cover at least one side of each of said contact modules and a second metallic shielding plate extending along the column direction to cover another side of each of said contact modules in the column direction; and

the first shielding plate of one contact module is unitarily joined with the first shielding plate of a neighboring contact module along the row direction as a first piece, and the second shielding plate of said one contact module is unitarily joined with the second shielding plate of the neighboring contact module along the column direction as a second piece intersecting with said first piece.

15. The electrical connector assembly as claimed in claim 14, wherein said first metallic shielding plate and said second metallic shielding plate are unitarily formed with each other as one piece.

16. The electrical connector assembly as claimed in claim 14, wherein said means includes legs extending below the conductive body for mounting to the printed circuit board on which the conductive body is seated.

17. The electrical connector assembly as claimed in claim 14, further including a second connector for mating with the first connector, wherein said second connector includes a plurality of wafers stacked with one another along the row direction, each wafer including a second conductive body enclosing a plurality of terminal modules each extending along a plane perpendicular to said row direction.

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